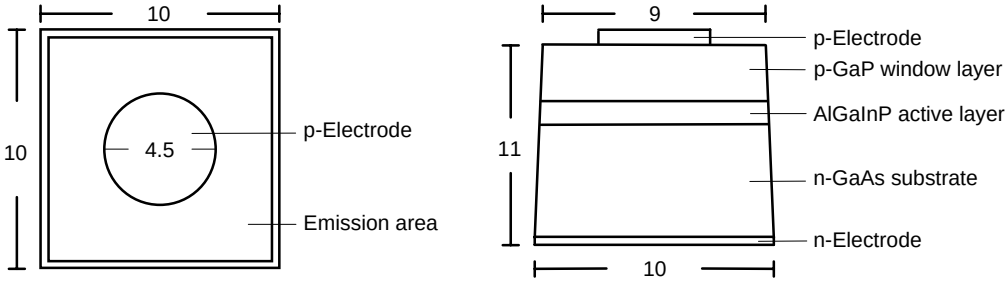
■ Features :

- HP MOVPE process wafer
- Superior VF and thermal stability
- High light output at four sides results high total light output and wide view angle after packaging
- High reliability
- Excellent bondability

■ Typical Applications :

- Automotive Signal Lamps: Front/ Rear Turns
- Automotive Interior Lighting
- Traffic Signal Modules/ Traffic Signs
- Message Signs
- Alternative to Incandescent Lamps
- Industrial Products

■ Outline Dimensions : (Unit: mil)



■ Physical Structure :

Chip dimension	Chip size	10.0 mils x 10.0 mils
	Thickness	11.0 mils
	Emission area	9.0 mils
	Bonding pad	4.5 mils
Electrode	Top: P (anode)	Aluminum
	Backside: N (cathode)	Gold alloy
Surface condition	Not frosted	

■ Electro-Optical Characteristics : (Ta = 25℃)

Parameter	Symbol		Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F		I_F = 20 mA	-	1.95	2.50	V
Reverse Voltage	V_R		I_R = 10 μA	5	-	-	V
Wavelength	λ_D		I_F = 20 mA	-	590	-	nm
	Hue			576	586	596	
Spectral width at half height	$\triangle\lambda$		I_F = 20 mA	-	18	-	nm
Luminous Intensity	I_V	B1	I_F = 20 mA	25	-	-	mcd
		C1		35	-	-	
		D1		45	-	-	

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■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

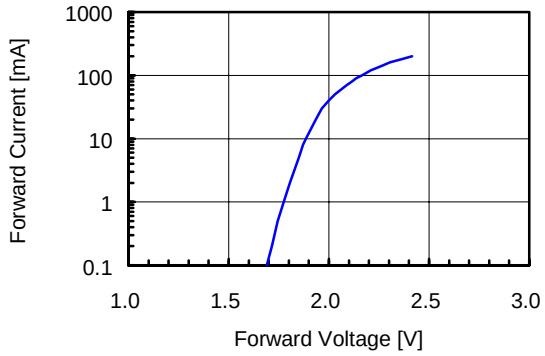


Fig 2. Relative Intensity vs. Forward Current

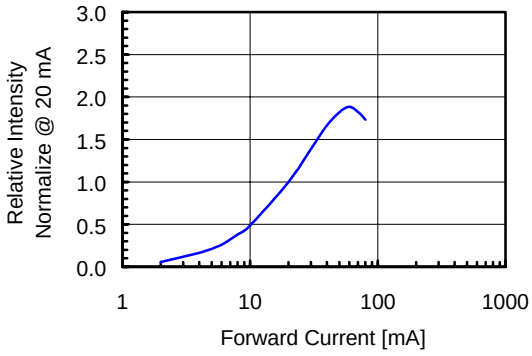


Fig 3. Forward Voltage vs. Temperature

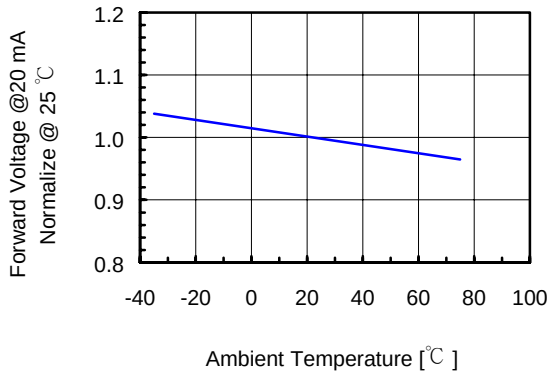


Fig 4. Relative Intensity vs. Temperature

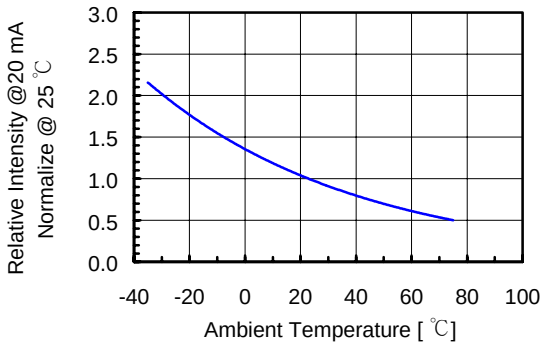
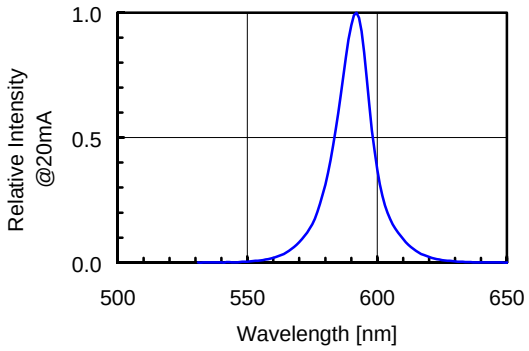


Fig 5. Relative Intensity vs. Wavelength



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